

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the inventor's name to Te-Hyun Kim instead of Te Hyun Kim with a dash between Te & Hyun previously recorded on Reel 014757 Frame 0269. Assignor(s) hereby confirms the inventor's name is Te-Hyun Kim, as listed correctly on all other application documents.
CONVEYING PARTY DATA	
Name	Execution Date
Te-Hyun KIM	11/20/2003
RECEIVING PARTY DATA	
Name:	LG ELECTRONICS INC.
Street Address:	20, YOIDO-DONG, YOUNGDUNGPO-GU
City:	Seoul
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	10724557
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	2060-3-91
NAME OF SUBMITTER:	Puya Partow-Navid, Esq.
Total Attachments: 2 source=2060-3-91-Assignment_Cover#page1.tif source=2060-3-91-Assignment_Cover#page2.tif	

CH \$40.00 10724557

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PATENT
REEL: 024661 FRAME: 0867

RECORDATION FORM COVER LETTER
PATENTS ONLY

To the Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Te Hyun Kim

2. Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: November 20, 2003

2. Name and address of receiving party(ies):

LG Electronics Inc.
20, Yoido-dong, Youngdungpo-gu
Seoul, Korea

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s): FILED HEREWITH

If this document is being filed together with a new application, the execution date of the application is: November 20, 2003

A. Patent Application No.(s) N/A

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

AMIT SHETH, ESQ.
LEE, HONG, DEGERMAN, KANG & SCHMADEKA P.C.
801 S. FIGUEROA STREET, 14TH Floor
LOS ANGELES, CALIFORNIA 90017

6. Total number of applications and patents involved: [1]

7. Total fee (37 CFR 3.41) \$40

- ☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number: 502290

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.


AMIT SHETH, REG. NO. 50,176

Date: November 26, 2003

OMB No. 0651-0011 (exp. 4/94)

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
Director – U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

ASSIGNMENT

(1-8) Insert Name(s) of Inventor(s) (1) Te-Hyun KIM (5)
(2)
(3)
(4) (6)
(7)
(8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) Insert name of Assignee (9) LG Electronics Inc.
(10) Insert state of Incorporation of Assignee (10) Republic of Korea
(11) Insert address of Assignee (11) 20, Yoido-dong, Youngdungpo-gu
Seoul, Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number (12) **STRUCTURE AND OPERATION METHOD OF BATTERY PACK**
for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

(13) Insert Date of Signing of Application (13) November 20, 2003

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.
The undersigned hereby appoints JONATHAN Y. KANG, REG. NO. 38,199; F. JASON FAR-HADIAN, REG. NO. 42,523; AMIT S. SHETH, REG. NO. 50,176; RICHARD K. YOON, REG. NO. 42,247; EDWARD GRAY, REG. NO. 35,166

the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: Nov. 20, 2003 Signature of Inventor: Tehyun Kim
Date: _____ Signature of Inventor: _____
Date: _____ Signature of Inventor: _____
Date: _____ Signature of Inventor: _____